



**(3583)**

**2020/11/18**

# Safe Harbor Statement

- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.

# Sciencetech Corp (3583: TT)



Company Establishment	1979/10/17
IPO	2013/3/12
Capital	NT\$ 811 Million
Chairman	H.L. Hsieh
President	M.T. Hus
Products	Equipment Manufacturing 、 Wafer Reclaim 、 Trading(Agent/Distributor)

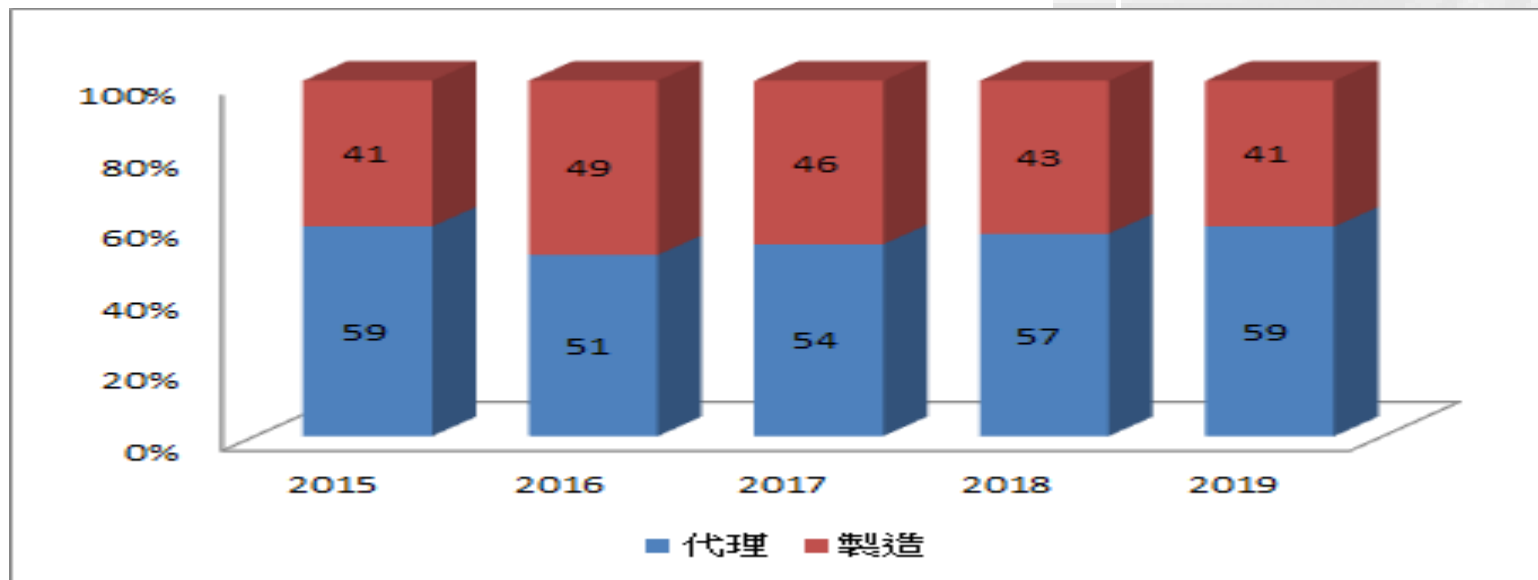
Business  
Overviews

Products

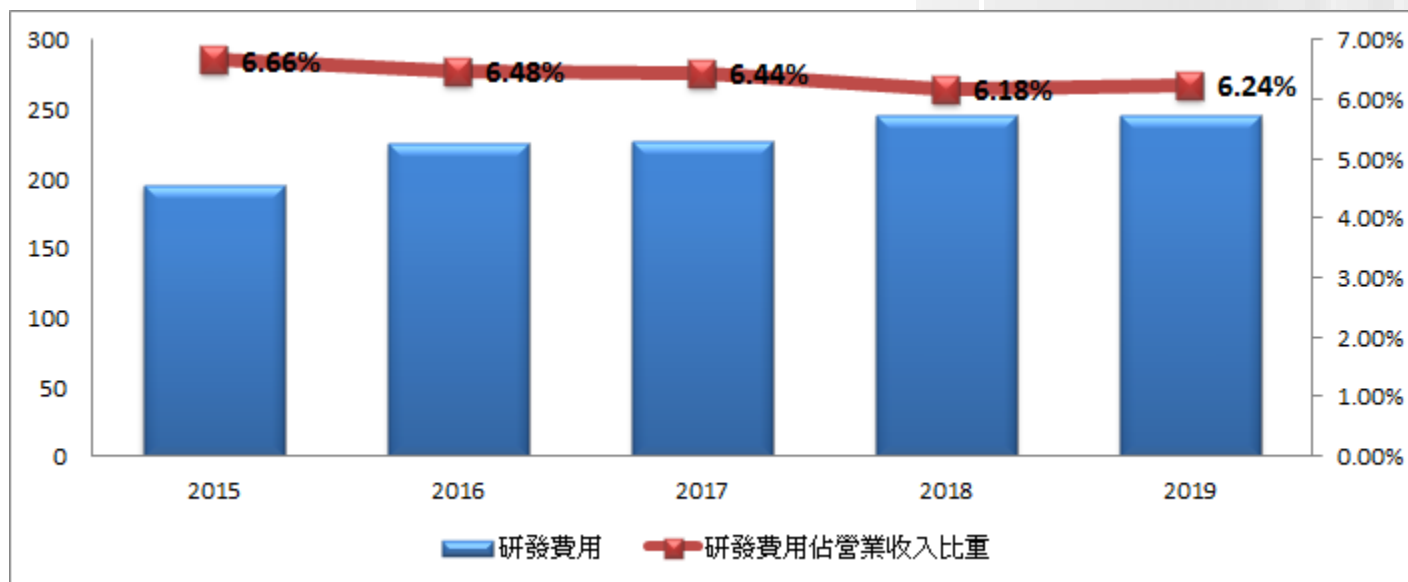
Future  
Prospect

Units : NT \$ M	2015	2016	2017	2018	2019	1Q~3Q20
Revenues	2,942	3,495	3,539	3,988	3,949	2,441
Gross Profit	903	1,178	1,251	1,448	1,384	1,023
Operating Expenses	779	835	829	935	997	717
Operating Income	124	343	423	514	387	306
Other Income and Expenses	(6)	21	(8)	26	16	(48)
Income Before Tax	119	363	415	540	403	258
Net Income	86	292	328	418	323	201
EPS	1.06	3.60	4.05	5.16	4.02	2.50
Gross Margin	30.69%	33.71%	35.36%	36.32%	35.05%	41.91%
Operating Margin	4.23%	9.80%	11.95%	12.88%	9.81%	12.55%
Income Before Tax margin	4.03%	10.40%	11.72%	13.54%	10.22%	8.22%

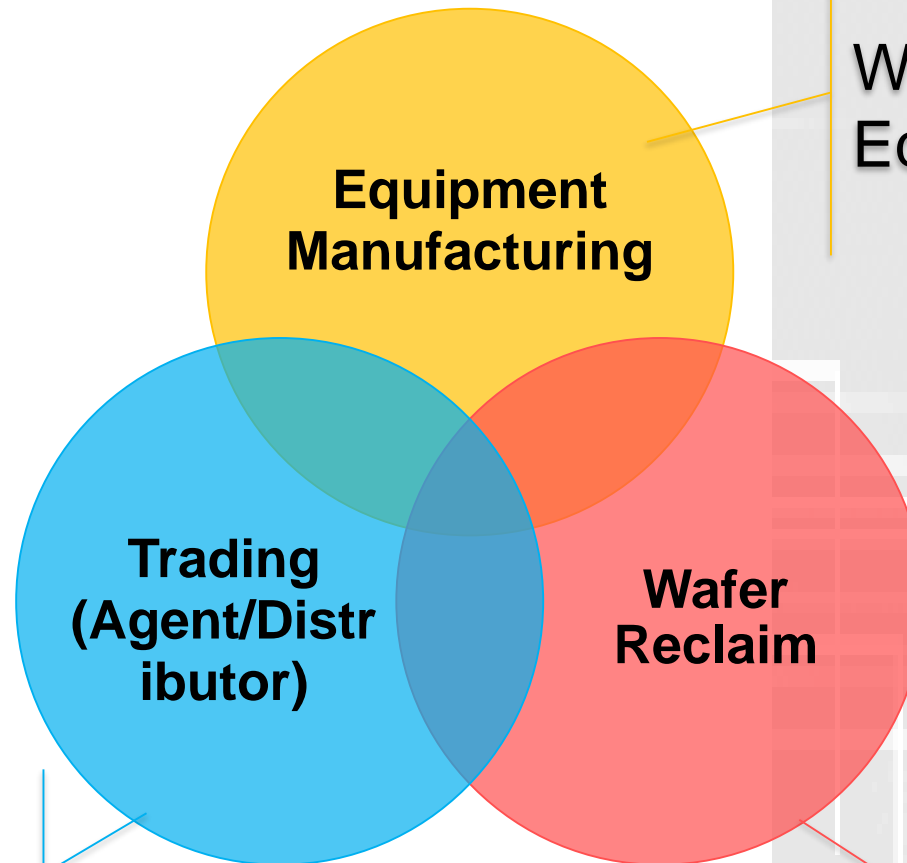
Units : %	2015	2016	2017	2018	2019	Gross Margin
Trading	59	51	54	57	59	Below Average
Manufacturing	41	49	46	43	41	Above Average



Units : NT \$ M	2015	2016	2017	2018	2019
R&D Expenses	196	226	228	246	246
Expenses as % of Revenue	6.66%	6.48%	6.44%	6.18%	6.24%



# Products



Wet Process  
Equipment

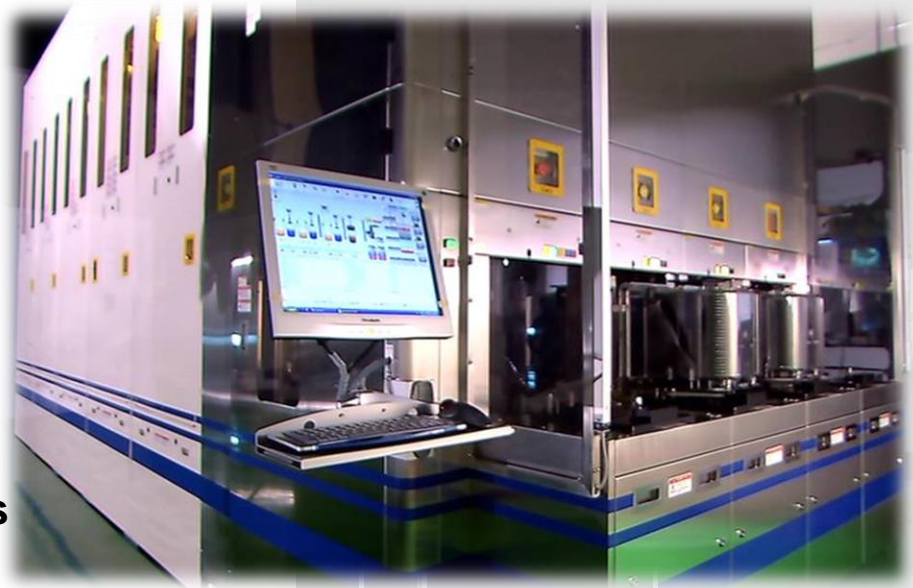
Semiconductor and  
Optoelectronics  
Process Equipment

12" Wafer  
Reclaim



## Wet process equipment

- **Single wafer/ Batch type**
  - ◆ **8"/12' Advanced packaging**  
(Fan-out 、 Solder Bump 、  
Copper Pillow 、 Bumping 、  
Gold Bump 、 RDL 、 TSV  
...ect)
  - ◆ **6"/ 8"/12" Front-end special  
process** (IoT Sensor 、 Power IC  
FP sensor 、 RF 、 CMOS 、 Touch  
Controller 、 MEMS)
  - ◆ **HB LED fully-automatic process**
  - ◆ **MEMS**
  - ◆ **III-V**



- 12" Wafer Reclaim
- Capacity: 120K / month
- Separated Cu & Non Cu Line

**Advanced clean technology**  
20nm/ 16nm Particle  
Low trace metal (<5E9)



**Complete particle inspection**  
(SP1-DLS & SP2)

*Cleaning*

*Etching*

***Full Process  
Optimization***

*Polishing*

*Grinding*

**Complete polishing process**  
Single side polish  
Double, side polish  
Final Haze polish

**Super flatness**  
(GBIR<0.5 $\mu$ m)



# Products

# Trading (Agent/Distributor)



ECO-SNOW SYSTEMS

PONGSAN MICROTEC

Canon



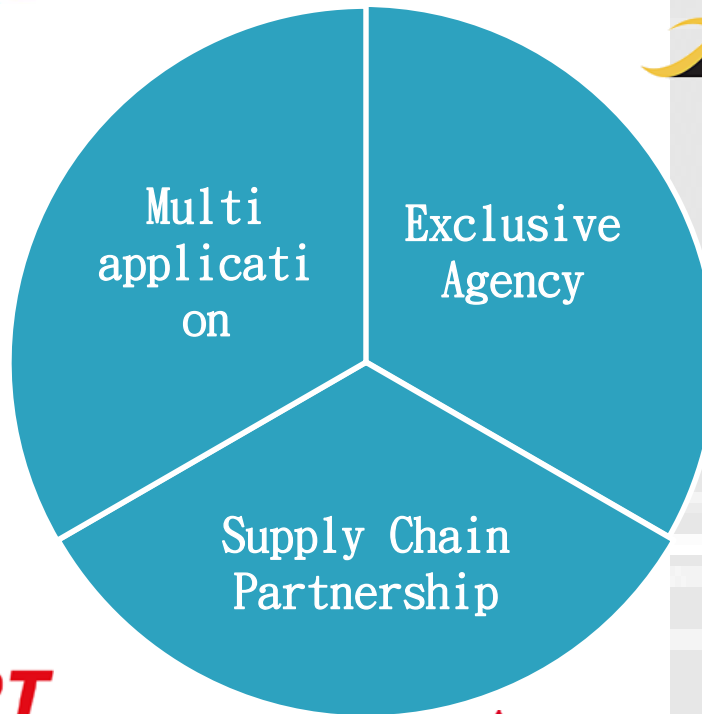
FerroTec

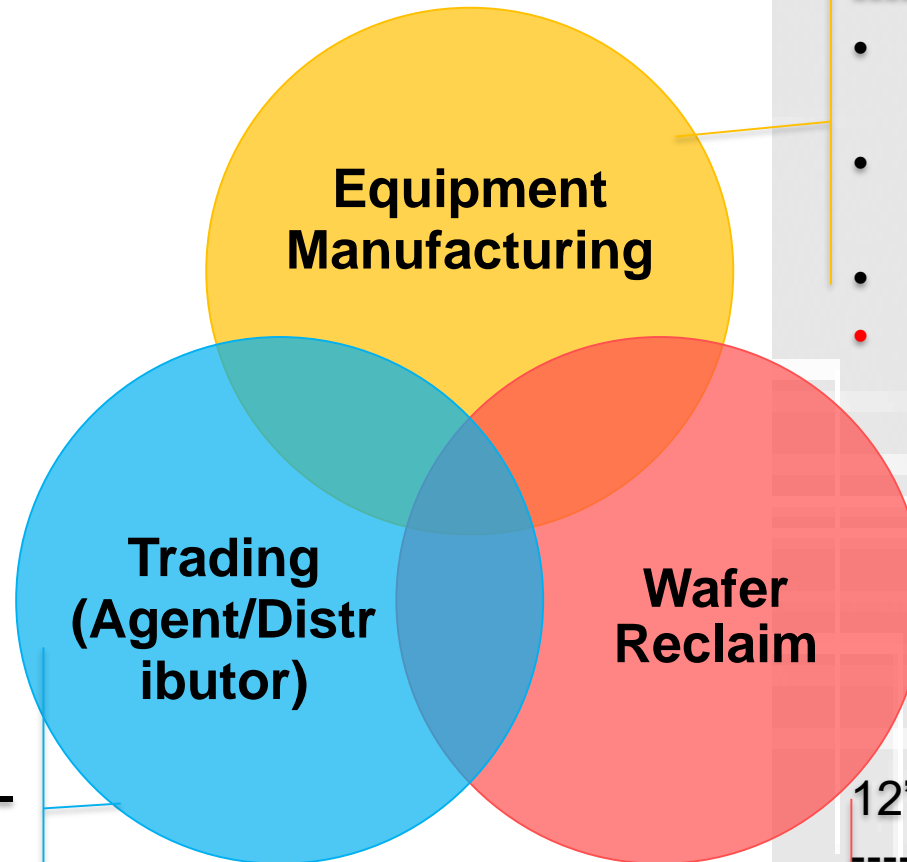


Hirata

Plasma-Therm

USHIO





## Wet Process Equipment

- Front-end Wet Process Equipment
- Wafer Support System
- Wafer Reclaim
- **Mass Spectrometer**

## Semiconductor and Optoelectronics Process Equipment

- **AMOLED**
- **Advanced Process Miniaturization**

## 12" Wafer Reclaim

- **China Manufacturing Base**
- **SiC Wafer Reclaim**

# Q & A



## Thank You!